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## Additive Manufacturing: Simulation of Distortion for Different Processes

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# COMSOL CONFERENCE 2016 MUNICH

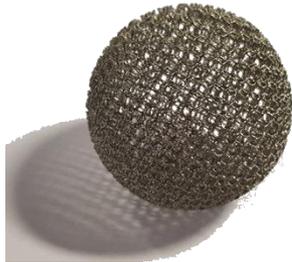


CATAPULT  
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# ADDITIVE LAYER MANUFACTURING (ALM)

## Powder-Based ALM:

- ▶ Selective Laser Melting (SLM)
- ▶ Electron Beam Melting (EBM)
- ▶ The parts are built-up by locally melting a thin layer of metal powder
- ▶ High accuracy
- ▶ Localised heat affected zone
- ▶ Slow build up time



**Top:** Hollow sphere built with a 3D lattice

**Bottom:** Calibration specimen used for FEA modelling of Powder-Based ALM



## Shaped Metal Deposition ALM:

- ▶ The desired shape is achieved by welding a continuous metal wire onto a substrate
- ▶ Larger deposition rates
- ▶ Accepts dissimilar materials
- ▶ Large heat affected zone



**Layer 1:** Neat first deposit



**Layer 2:** Visible sliding of molten layers



**Layer 6:** Observable distortion in substrate

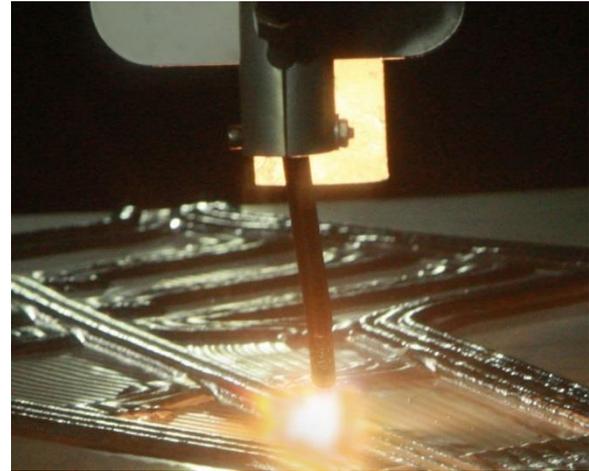
# WHY MODEL ALM PROCESSES?

ALM processes are not fully understood due to their complexity

- ▶ Many heat cycles are involved, which remove/overwrite temperature history
- ▶ Complicated microstructure evolution of alloy materials
- ▶ Undesired distortion and residual stresses

Modelling can help identify:

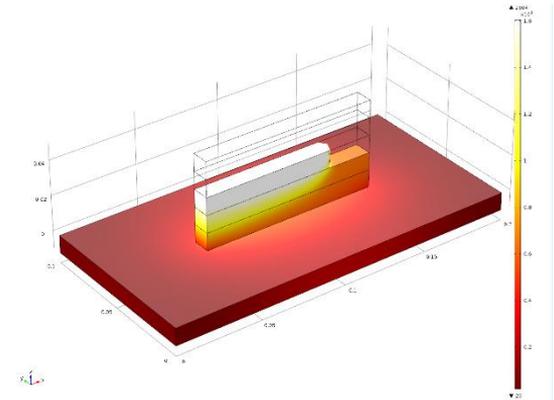
- ▶ A suitable calibrated material model
- ▶ Methods to reduce residual stresses and distortion
  - ▶ Through parametric studies of key process parameters, which can include heating or cooling effects



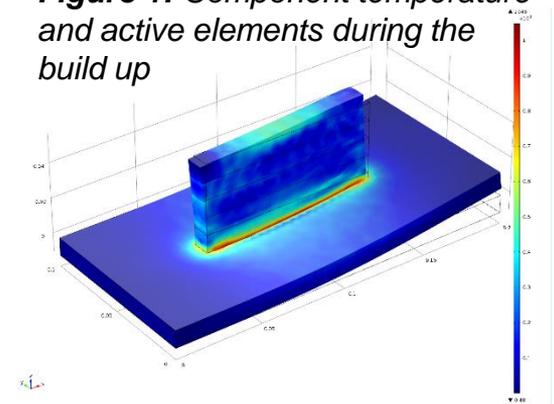
<http://additivemanufacturing.com/2013/03/25/scia-kys-dm-solution-game-changing-technology/>

# THERMOMECHANICAL MODEL

- ▶ Domain ODE + previous solution
  - ▶ The field variable controls the “activation” of the newly molten material based on the tool position and current layer height; maintaining it active once the pass is complete
- ▶ Heat Transfer
  - ▶ Moving heat source
  - ▶ External convection/radiation to the environment
- ▶ Structural Mechanics
  - ▶ Clamping and unclamping of the part
  - ▶ Elastoplastic material model
- ▶ Thermal Expansion Coupling
- ▶ Sequentially-coupled
  - ▶ Activation → Heat Transfer → Structural Mechanics

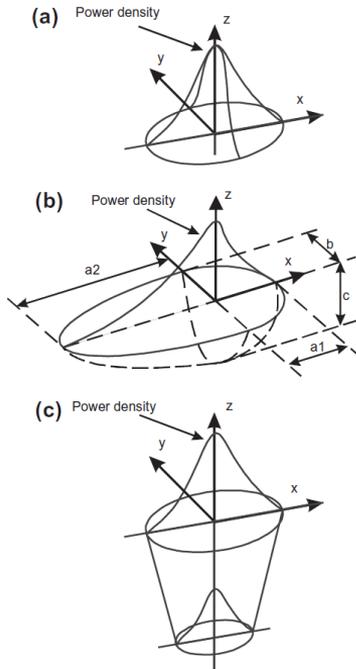


**Figure 1:** Component temperature and active elements during the build up



**Figure 2:** Residual stresses after release (Von Mises)

# HEAT SOURCE MODELS



## a) Surface Disk Source

$$q(r) = q(0)e^{-Cr^2}$$

## b) Goldak Double Ellipsoid Source

$$q_f(x, y, z, t) = \frac{6\sqrt{3}f_f Q}{abc_f \pi \sqrt{\pi}} \exp\left(-3\left(\frac{x^2}{a^2} + \frac{y^2}{b^2} + \frac{(z - (vt))^2}{c_f^2}\right)\right)$$

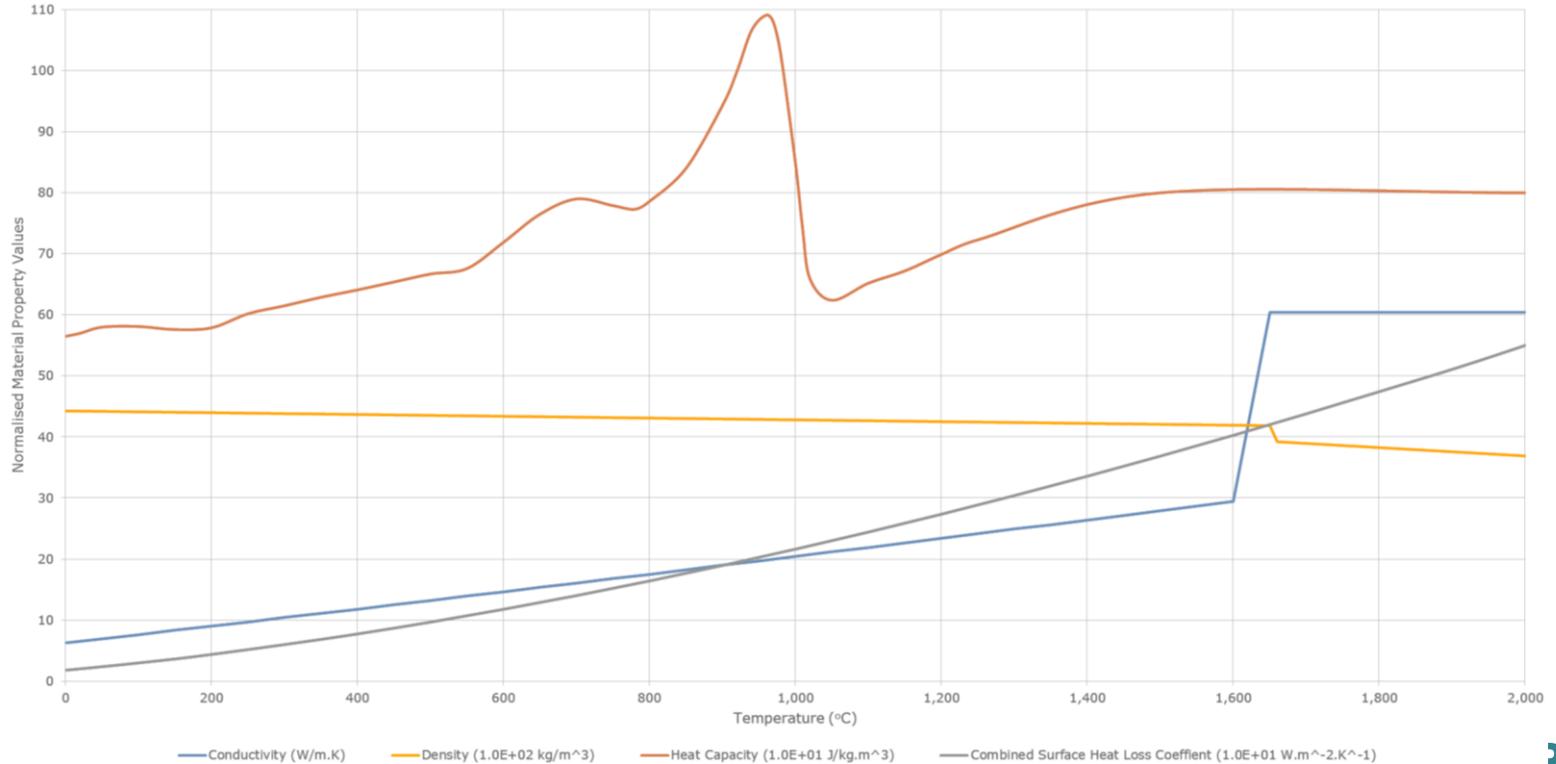
$$q_r(x, y, z, t) = \frac{6\sqrt{3}f_r Q}{abc_r \pi \sqrt{\pi}} \exp\left(-3\left(\frac{x^2}{a^2} + \frac{y^2}{b^2} + \frac{(z - (vt))^2}{c_r^2}\right)\right)$$

## c) Conical Heat Source

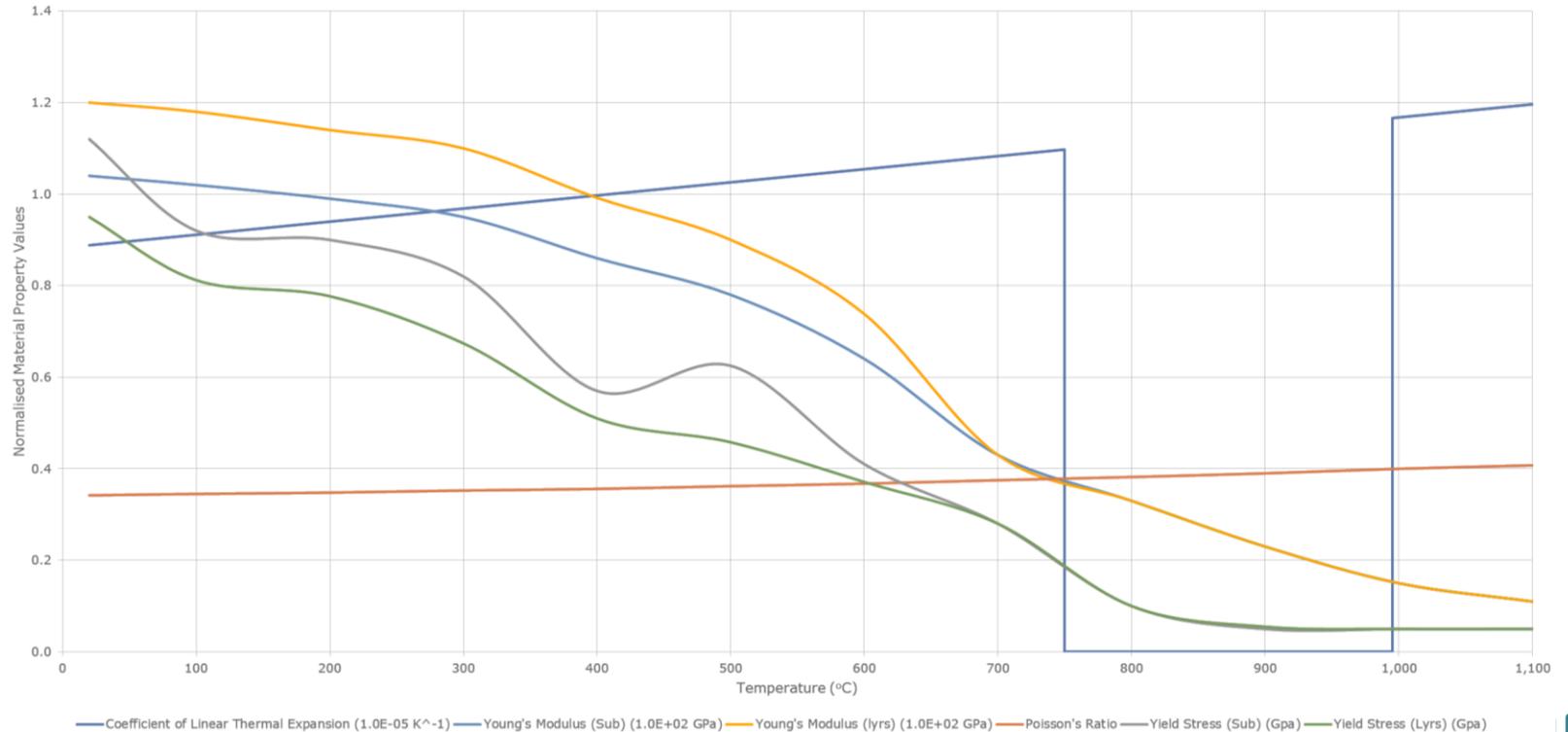
$$q_v(x, y, z, t) = \frac{2\eta\beta Q}{\pi r_0^2 d_0} \exp\left[1 - \left(\frac{x^2 + (z - (vt))^2}{r_0^2}\right)\right] \left(1 + \frac{y}{d_0}\right)$$

P. Lacki, K. Adamus, K. Wojsyk, M. Zawadzki, Z. Nitkiewicz, Modelling of Heat Source Based on Parameters of Electron Beam Welding Process, *Archives of Metallurgy and Materials* 56 (2) (2011) 455-462.

# MATERIAL PROPERTIES (THERMAL)



# MATERIAL PROPERTIES (STRUCTURAL)



# MODEL SUITABILITY

## Shaped Metal Deposition ALM:

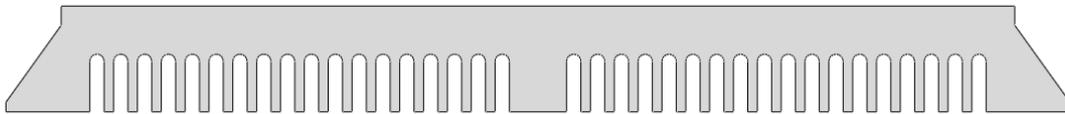
- ▶ Melt pool / layer dimensions are not too small compared to overall part
- ▶ Larger heat affected zones can see a benefit to using detailed material models
- ▶ Full 3D models can be solved within a reasonable timescale (~ 1 day)

## Powder-Based ALM:

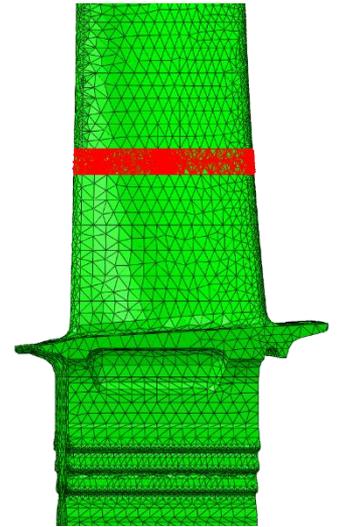
- ▶ Powder layer thickness is typically tens to hundreds of microns
- ▶ Industrial components have typically tens of centimetres
- ▶ Real industrial example:  
Design: 25 cm x 20 cm x 20 cm = 0.01 m<sup>3</sup>  
Regular element: (50 μm)<sup>3</sup> = 1.25E-13 m<sup>3</sup>  
Required elements: **8E10**
- ▶ Not a suitable solution, an alternative is required

# LUMPED THERMAL STRESS MODEL

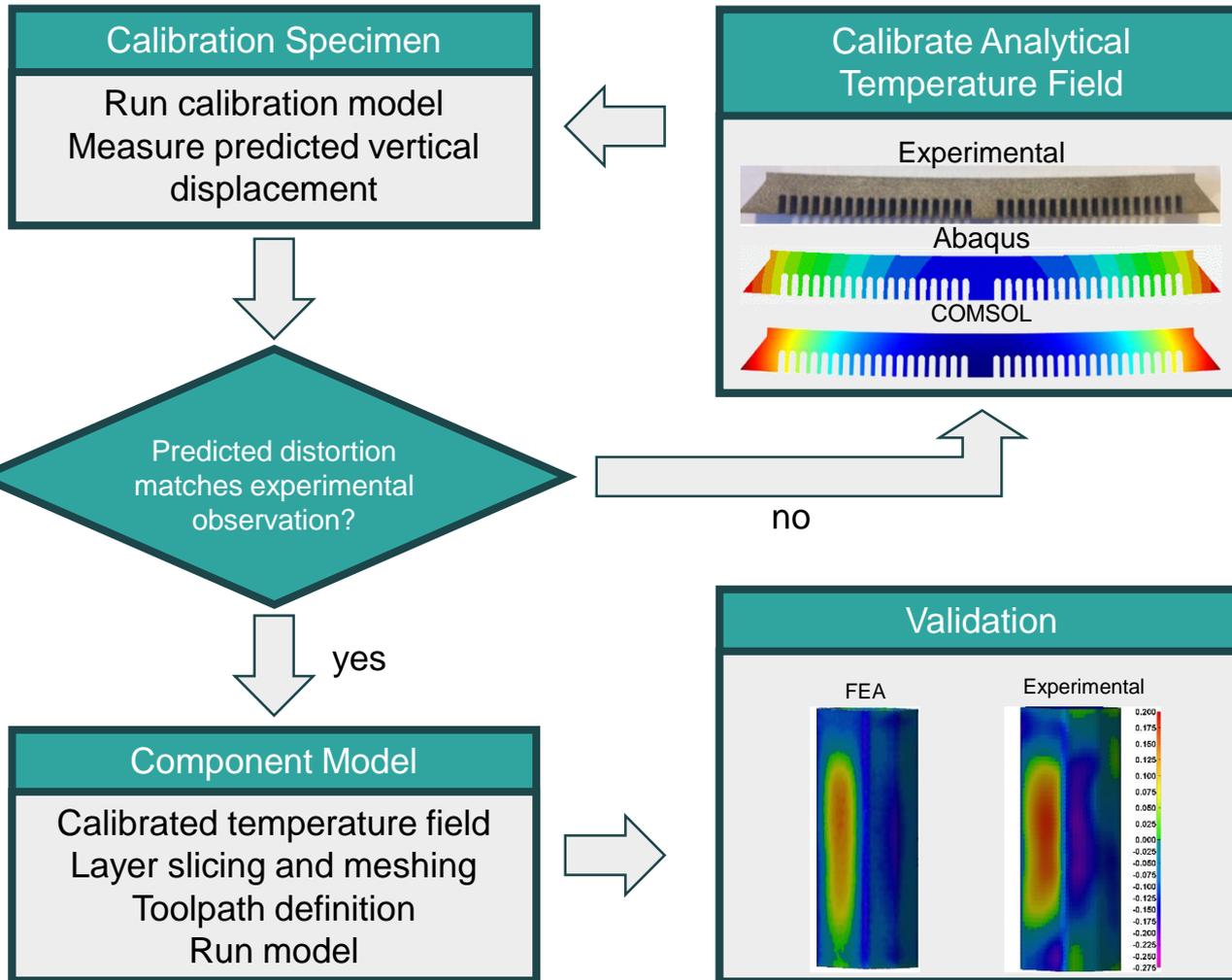
- ▶ When using a lumped layer approach we are no longer explicitly modelling the real process
- ▶ We have to use a specimen geometry to calculate the equivalent thermal strain required per lumped layer to deform the component as observed in reality
- ▶ The MTC approach involves calibrating an analytical temperature field to induce the appropriate thermal strain



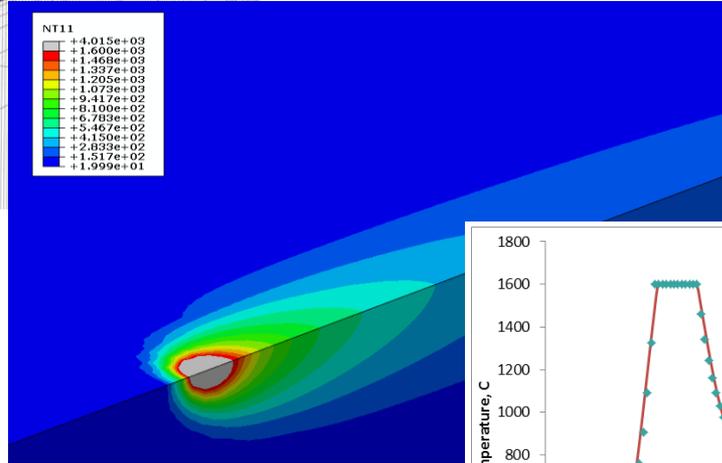
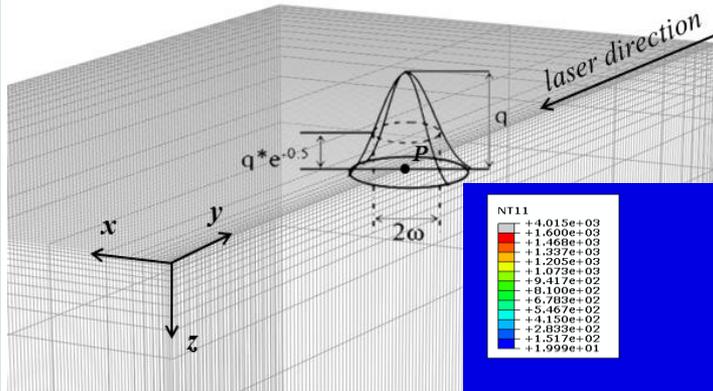
**Figure 1:** 2D calibration specimen geometry



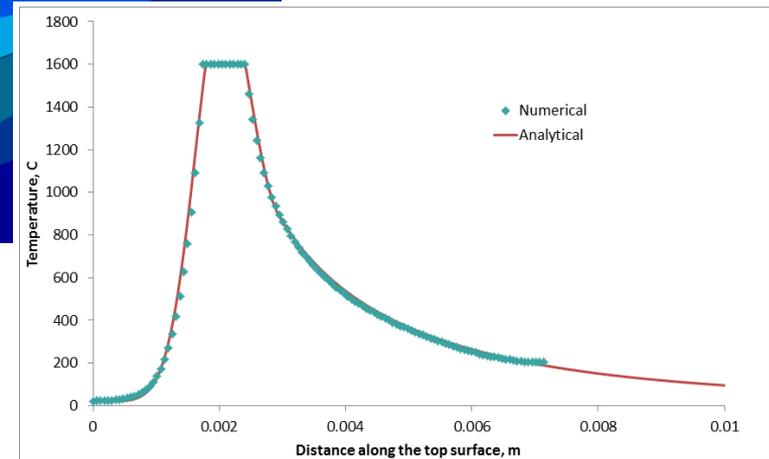
**Figure 2:** 3D blade geometry with highlighted lumped layers, corresponding to 6 real powder layers in this thickness



# TEMPERATURE FIELD CALIBRATION



Information Flow



# ANALYTICAL TEMPERATURE FIELD

► The temperature field used in the MTC model is given by:

$$T(x, y, z) = T_{amb} + \frac{2Q}{C_p \rho (4\pi a t_{ref})^{\frac{3}{2}}} \exp\left(-\frac{(x-x')^2 + (y-y')^2 + (z-z')^2}{4at_{ref}}\right)$$

$T_{amb}$  Ambient temperature

$Q$  Heat source power\*

$\rho$  Material density (room temperature)

$C_p$  Material heat capacity (room temperature)

$a$  Material thermal diffusivity ( $k/\rho C_p$ ) (room temperature)

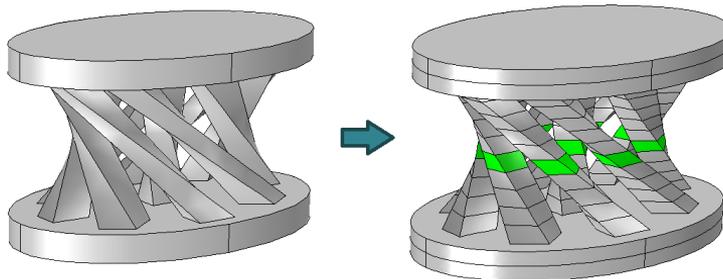
$t_{ref}$  Reference time\*

$\{x', y', z'\}$  Current heat source centre coordinates

\* Parameters which are used to calibrate temperature field

# FULL COMPONENT SLICING AND MESHING

- ▶ Once the temperature field is calibrated it can be applied to the actual component
- ▶ Before meshing, the geometry needs to be sliced to the thickness of the layer lumping used for the calibration specimen
- ▶ The part can then be meshed using a similar element size to the specimen

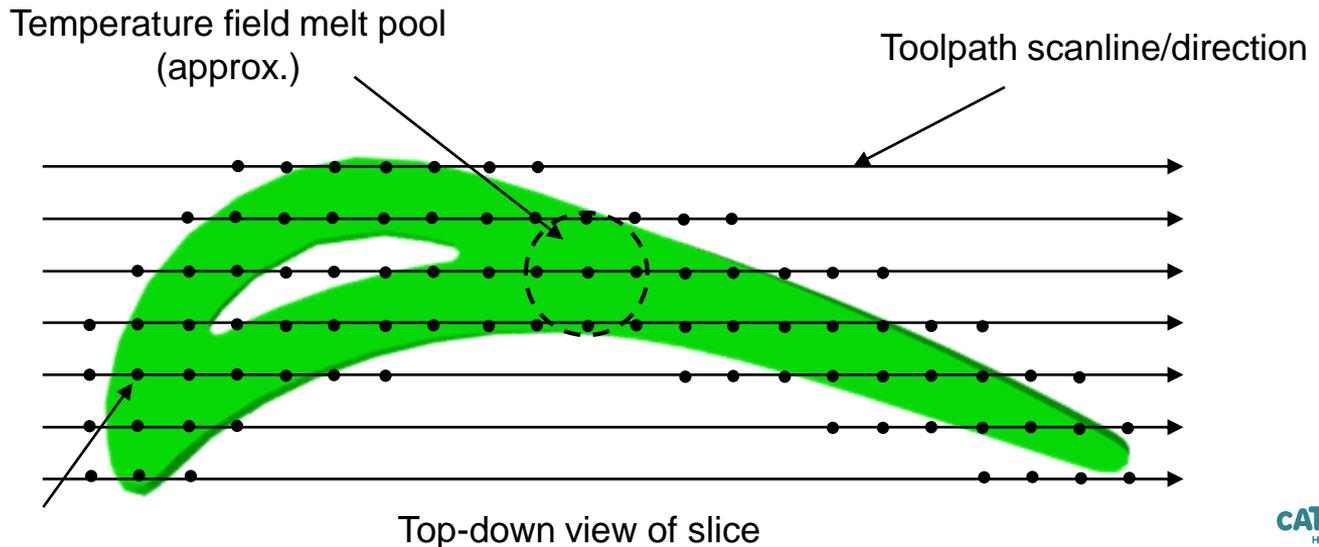


*Left: Original geometry*

*Right: Sliced geometry using a COMSOL App.  
The domains of one slice are highlighted.*

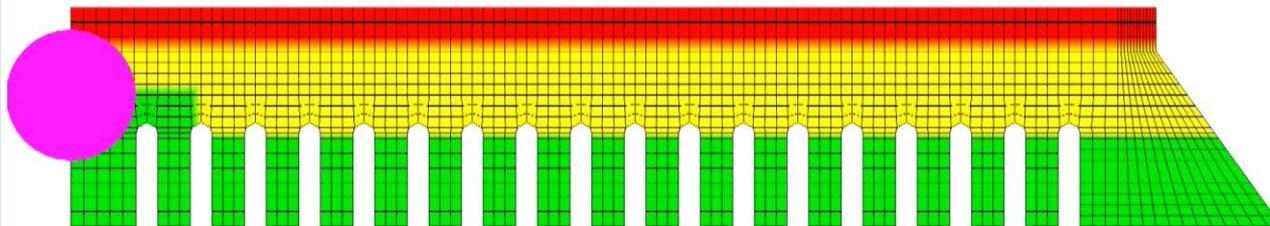
# TOOLPATH GENERATION

- ▶ From observation, the toolpath has little impact on the overall result and we have found that toolpath waypoints lying on simple linear 'stripes' are suitable



# ACTIVE, SOFT AND HARD ELEMENTS

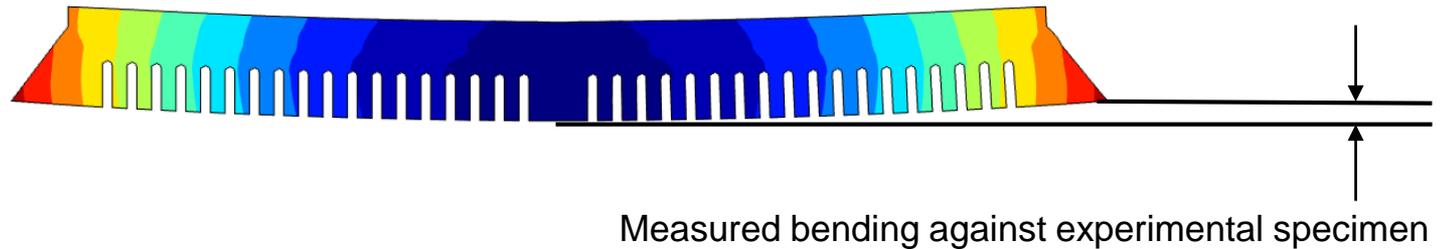
- ▶ Layers which are above the current heat source location are treated as deactivated or “quiet” and are given soft properties
- ▶ The current layer starts in an inactive state and a search radius is applied around the temperature field centre to activate nearby elements as they are deposited
- ▶ In the real process, the laser will always scan in the expected location of the target geometry regardless of any deformation experienced
- ▶ To emulate this, a soft element layer connects the current layer with a rigid and constrained area.



**Green:** Active  
**Yellow:** Soft (quiet)  
**Red:** Rigid  
**Magenta:** Melt pool

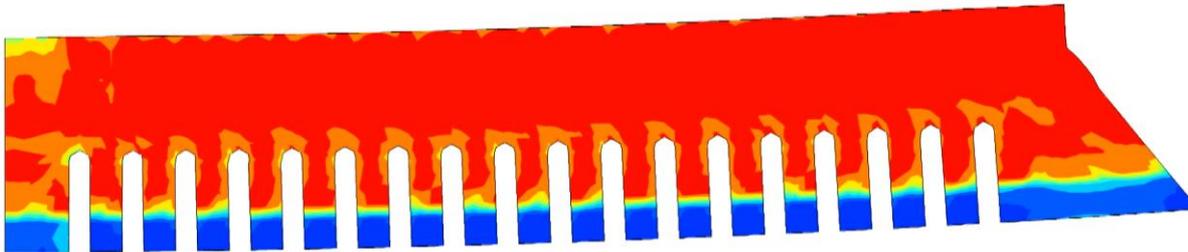
# SPECIMEN EXPERIMENTAL BUILD AND MEASUREMENT

- ▶ The specimen should be built using the same machine scan strategy and parameters which are intended for use in the real component
- ▶ The bending of the cantilever part should be measured in the build direction



## CALIBRATION MODEL

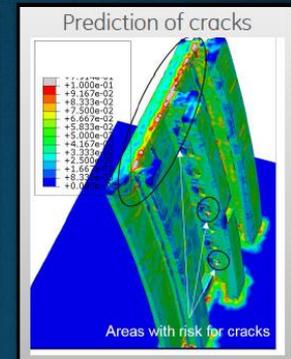
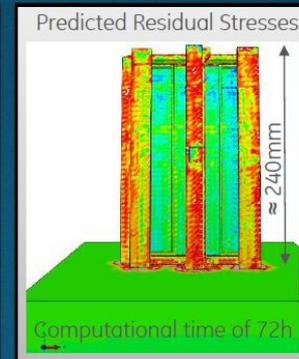
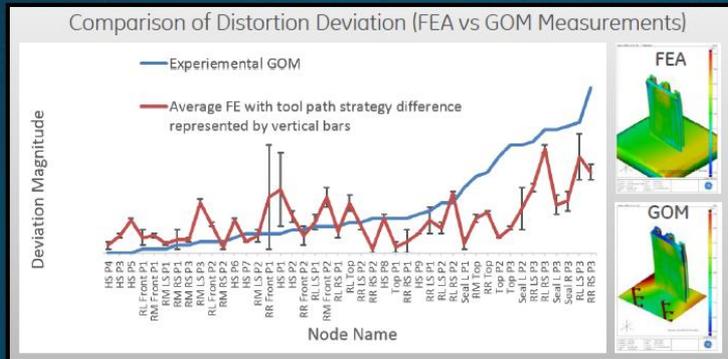
- ▶ The calibration model can make use of the 2D plane stress element formulation
- ▶ This allows very quick iterations (typically 1-2 minutes) of the temperature field to calibrate against experimentally observed deformation
- ▶ Symmetry can be exploited



*Video: Von Mises stress during build and release.*

# Additive Manufacture Process Simulation

- MTC, developed novel, finite element modelling of additive manufacture and prediction of distortion, residual stresses and risks of cracks.
- Good agreement between numerically predicted and experimentally measured trends and patterns of distortion, particularly the magnitudes of distortion.
- Predicted areas where the heat shield exhibited significant risk of cracking through equivalent plastic strains.
- Residual stresses were predicted for two tool path strategies.



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**Case study:** Presented at NAFEMS Conference in June 2016 by Charles Soothill (Senior Vice President of Technology and Chief Technical Officer at GE Power)

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